CHIPSUN
芯 阳 科 技

CSN9F064

N-Ch 60V Fast Switching MOSFETs

General Description

The CSN9F064 is the highest performance trench N-ch MOSFETs with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The CSN9F064 meet the RoHS and Green Product requirement , 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available
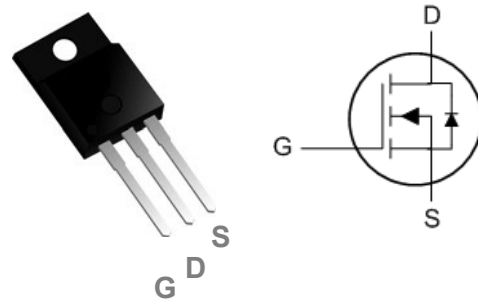
Product Summery

Green

BVDSS	RDSON	ID
60V	12mΩ	38A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

TO220F Pin Configuration

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	60	V
V_{GS}	Gate-Source Voltage	±20	V
I_D@T_C=25℃	Continuous Drain Current, V_{GS} @ 10V[1]	38	A
I_D@T_C=100℃	Continuous Drain Current, V_{GS} @ 10V[1]	24	A
I_D@T_A=25℃	Continuous Drain Current, V_{GS} @ 10V[1]	9.2	A
I_D@T_A=70℃	Continuous Drain Current, V_{GS} @ 10V[1]	7.5	A
I_{DM}	Pulsed Drain Current[2]	95	A
EAS	Single Pulse Avalanche Energy[3]	123	mJ
I_{AS}	Avalanche Current	38	A
P_D@T_C=25℃	Total Power Dissipation[4]	34.7	W
P_D@T_A=25℃	Total Power Dissipation[4]	2	W
T_{STG}	Storage Temperature Range	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	℃

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient [1]	---	62	℃/W
$R_{\theta JC}$	Thermal Resistance Junction-Case[1]	---	3.6	℃/W

Electrical Characteristics (T_J=25 ℃, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250uA	60	---	---	V
$\triangle BV_{DSS}/\triangle T_J$	BV_{DSS} Temperature Coefficient	Reference to 25℃ , I_D=1mA	---	0.052	---	V/℃
$R_{DS(ON)}$	Static Drain-Source On-Resistance[2]	V_{GS}=10V , I_D=30A	---	10	12	mΩ
		V_{GS}=4.5V , I_D=15A	---	12	15	
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =250uA	1.2	---	2.5	V
$\triangle V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-5.76	---	mV/℃
I_{DSS}	Drain-Source Leakage Current	V_{DS}=48V , V_{GS}=0V , T_J=25℃	---	---	1	uA
		V_{DS}=48V , V_{GS}=0V , T_J=55℃	---	---	5	
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±20V , V_{DS}=0V	---	---	±100	nA
gfs	Forward Transconductance	V_{DS}=5V , I_D=30A	---	42	---	S
R_g	Gate Resistance	V_{DS}=0V , V_{GS}=0V , f=1MHz	---	1.5	3	Ω
Q_g	Total Gate Charge (4.5V)		---	28.7	40.2	nC
Q_{gs}	Gate-Source Charge	V_{DS}=48V , V_{GS}=4.5V , I_D=15A	---	10.5	14.7	
Q_{gd}	Gate-Drain Charge		---	9.9	14.0	
$T_{d(on)}$	Turn-On Delay Time		---	10.4	20.8	ns
T_r	Rise Time	V_{DD}=30V , V_{GS}=10V , R_G=3.3Ω, I_D=15A	---	9.2	16.6	
$T_{d(off)}$	Turn-Off Delay Time		---	63	126	
T_f	Fall Time		---	4.8	9.6	
C_{iss}	Input Capacitance		---	3240	4536	pF
C_{oss}	Output Capacitance	V_{DS}=15V , V_{GS}=0V , f=1MHz	---	210	294	
C_{rss}	Reverse Transfer Capacitance		---	146	204	

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
EAS	Single Pulse Avalanche Energy[5]	V_{DD}=25V , L=0.1mH , I_{AS}=30A	77	---	---	mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current[1,6]	V_G=V_D=0V , Force Current	---	---	38	A
I_{SM}	Pulsed Source Current[2,6]		---	---	95	A
V_{SD}	Diode Forward Voltage[2]	V_{GS}=0V , I_S=A , T_J=25℃	---	---	1.2	V
t_{rr}	Reverse Recovery Time	I_F=15A , dI/dt=100A/μs , T_J=25℃	---	18	---	nS
Q_{rr}	Reverse Recovery Charge		---	14	---	nC

Note :

1.The data tested by surface mounted on a 1 inch[2] FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%

3.The EAS data shows Max. rating . The test condition is V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=38A

4.The power dissipation is limited by 150℃ junction temperature

5.The Min. value is 100% EAS tested guarantee.

6.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.
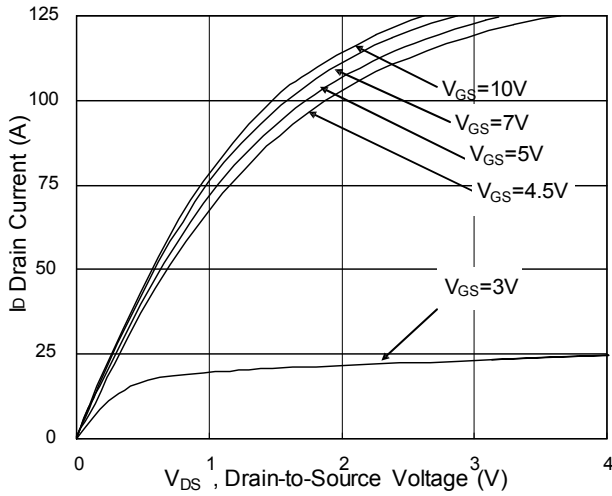
Typical Characteristics
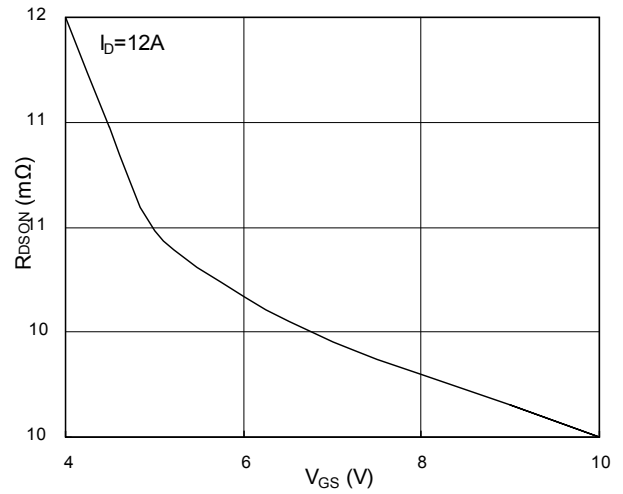

Fig.1 Typical Output Characteristics
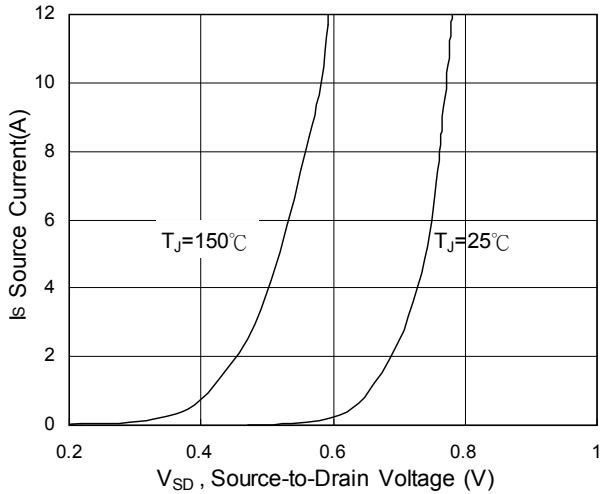

Fig.2 On-Resistance vs. Gate-Source Voltage
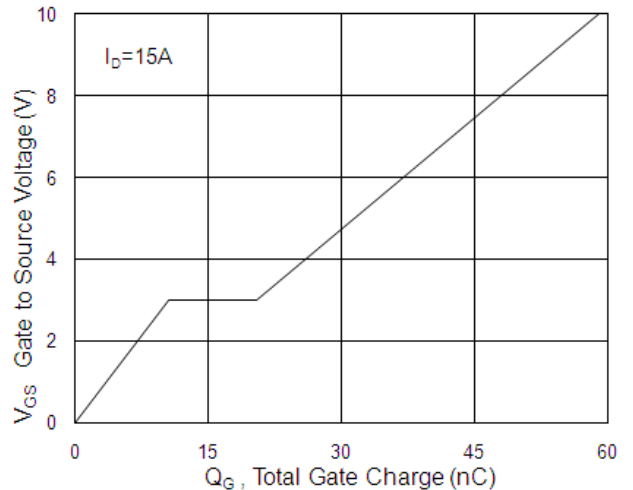

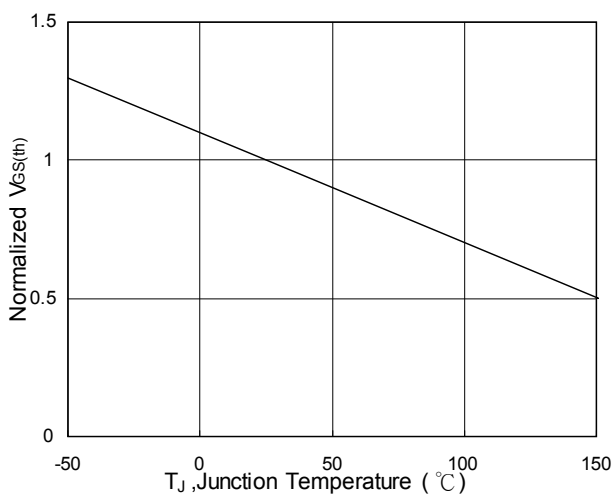**Fig.3 Forward Characteristics of Reverse**

Fig.4 Gate-Charge Characteristics

Fig.5 Normalized V_GS(th) vs. T_J
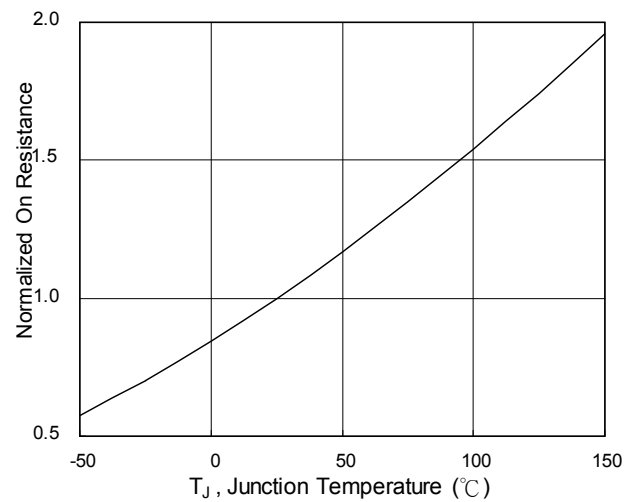
Fig.6 Normalized R_DSON vs. T_J
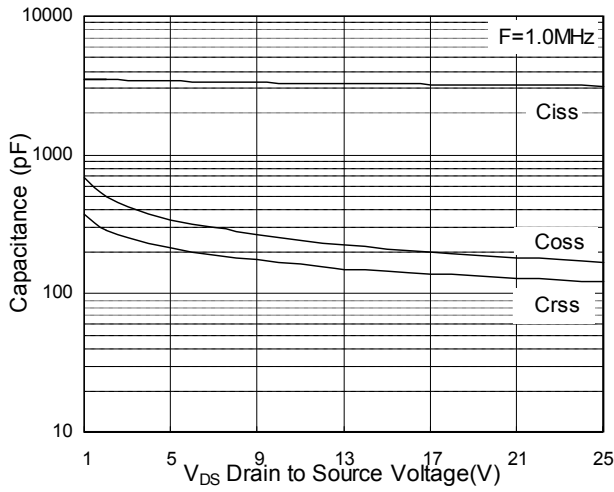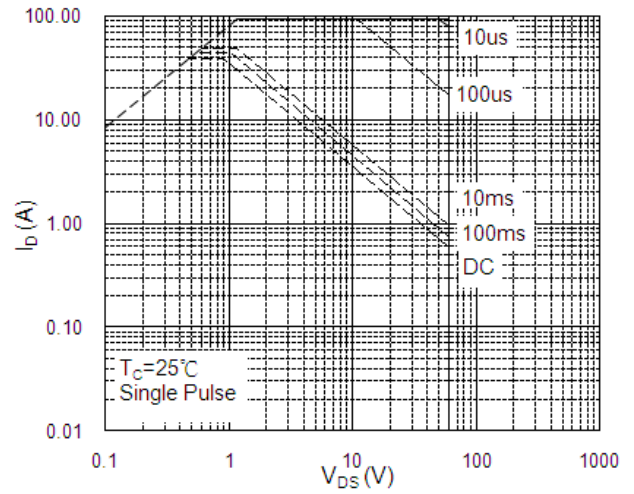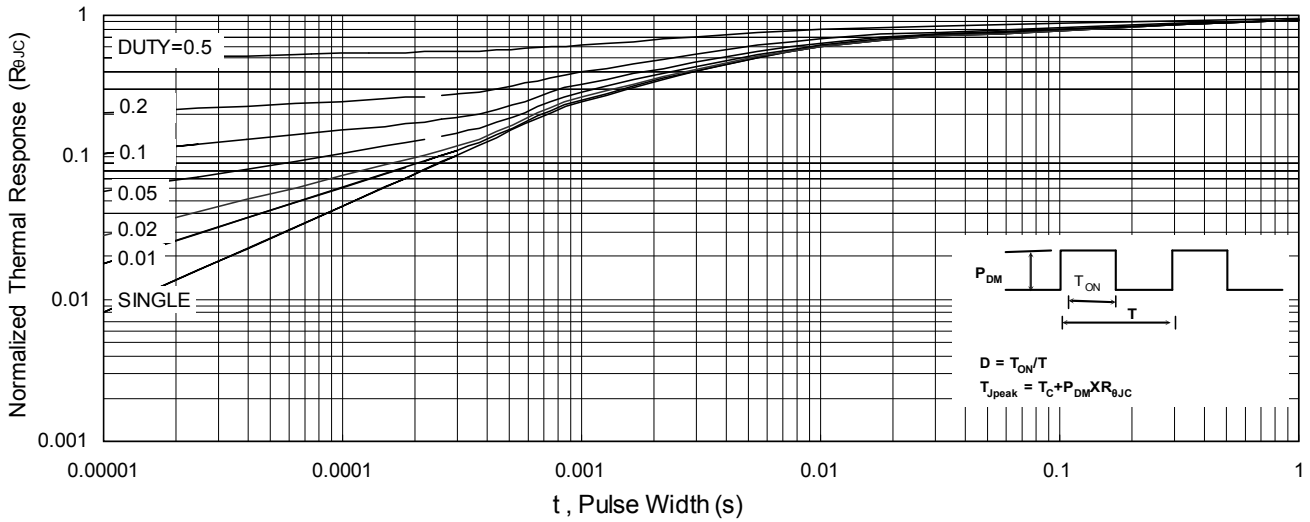
Fig.7 Capacitance

Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

$$D = T_{ON}/T$$
$$T_{Jpeak} = T_C + P_{DM} \times R_{\theta JC}$$
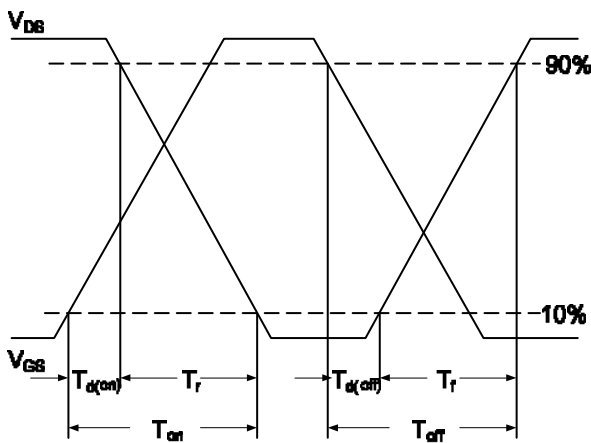
Fig.10 Switching Time Waveform

$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$
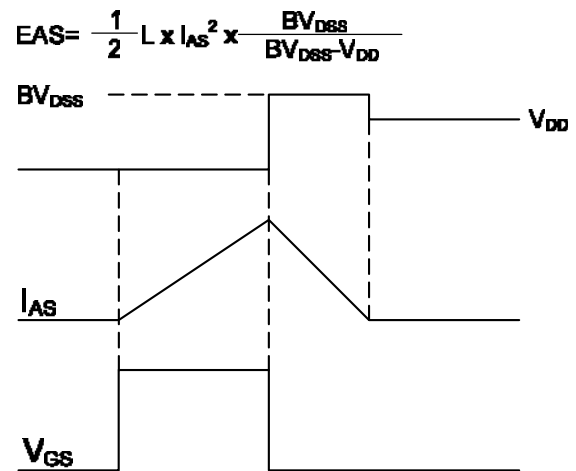
Fig.11 Unclamped Inductive Switching Waveform

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